



MOCVD LAB IN ENGINEERING CENTERS BUILDING

16C1Y



Summary – This project remodels suite 206d in the Engineering Centers Building for a new facility recruit involved in Metal Organic Chemical Vapor Deposition (MOCVD) used in the manufacturing of computer chips. It will be an H5 hazardous occupancy with intensive equipment needs.

▼ BUDGET

TOTAL \$ 756,000

FUNDING SOURCES

Gifts & Grants \$ 756,000

ESTIMATED BUDGET BREAKDOWN

Construction \$ 608,000

Design \$ 60,800

DFD Mgt. \$ 27,000

Contingency \$ 60,800

Equipment \$ 0

Other Fees \$ 0

Construction \$/GSF \$ N/A

Total Project \$/GSF \$ N/A

▼ TIMELINE

A/E Selection 04/2016

Planning N/A

Programming N/A

10% Concept Report N/A

35% Design Report 05/2016 – 07/2016

Construction Documents 07/2016 – 08/2016

Bid Date 12/2016

Construction 02/2017 – 09/2017

Substantial Completion 10/2017

Occupancy 10/2017

▼ AREA DATA

GSF N/A

ASF 1,320

Efficiency N/A

▼ ISSUES

There are currently issues for this project in the following areas:

- **Cost**
- **Schedule conflicts**

▼ KEY STAKEHOLDERS

Occupants College of Engineering

User Reps Sharon Devenick

UW PM Pete Heaslett

DFD PM Doug Schorr

A/E KEE Architects

Design Arch. N/A

Landscape Arch. N/A

Structural Engr. N/A

Delivery Method Design-Bid-Build Single Prime

General Miron Construction

Plumbing Hooper Corp.

Mechanical H & H

Fire Protection Ahern

Electrical Forward